



PRESS RELEASE

Contact: Jan Vardaman
(512) 372-8887

FOR IMMEDIATE RELEASE
May 31, 2013

SavanSys Solutions and TechSearch International Announce Release of 2.5D and 3D Packaging Cost Trade-off Model

After successful collaboration on cost models for Flip Chip, Wire Bond, Wafer Level Packaging, and other technologies, SavanSys Solutions and TechSearch International announce the release of a new cost trade-off model for 2.5D and 3D packaging technologies. While there are still technical barriers to high volume adoption of 2.5D and 3D packaging solutions, cost remains a primary obstacle. The question is not whether 2.5D and 3D stacks can be built, but rather which applications are appropriate for these technologies based on cost/performance.

The 2.5D and 3D Packaging Cost Trade-off Model covers the total cost and yield from fabrication of the wafer to complete assembly, for both 2.5D and 3D applications. The user is able to edit a variety of parameters, including TSV and interposer characteristics, supplier specific inputs, and die preparation details. For parameters not known or specified, the model will estimate it based on other user entries and the latest industry knowledge. A detailed cost break down of the total process cost is generated for each analysis, allowing the user to pinpoint the exact steps in the process flow that contribute to cost. In addition, detailed manipulation of the process flow is available, allowing the user to disable or enter specific values for process steps.

The model is currently in beta sites. For more information on the release schedule and purchasing details, please contact TechSearch International.

TechSearch International, Inc., founded in 1987, is market research leader specializing in technology trends microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 15,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887, fax: 512-372-8889, or <http://www.techsearchinc.com>.

SavanSys Solutions LLC is the industry expert on electronics manufacturing cost modeling. Using a combination of expert consulting services and the unique SavanSys modeling technology, SavanSys provides the electronics industry with solutions for supply chain cost modeling, new technology cost analysis, and a detailed understanding of the cost impact of design changes. For more information, contact SavanSys at tel: 512-402-9943, or <http://www.savansys.com>.